



INTERNATIONAL STANDARD



**Printed boards design, manufacture and assembly – Vocabulary –
Part 2: Common usage in electronic technologies as well as printed board and
electronic assembly technologies**

INTERNATIONAL
ELECTROTECHNICAL
COMMISSION

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CONTENTS

FOREWORD.....	3
1 Scope.....	5
2 Normative references	5
3 Terms and definitions	5
3.1 A.....	5
3.2 B.....	8
3.3 C	11
3.4 D	17
3.5 E.....	19
3.6 F.....	20
3.7 G	22
3.8 H	23
3.9 I.....	24
3.10 J	25
3.11 K.....	25
3.12 L	25
3.13 M	28
3.14 N	30
3.15 O	30
3.16 P.....	30
3.17 Q	34
3.18 R	35
3.19 S.....	37
3.20 T.....	40
3.21 U	41
3.22 V.....	42
3.23 W.....	42
3.24 Z.....	43
Bibliography.....	44
Figure 1 – Ball grid array (BGA).....	9
Figure 2 – Bumped die.....	11
Figure 3 – Chip on board (COB).....	13
Figure 4 – Flip chip	22
Figure 5 – Histogram	23
Figure 6 – Leaded surface-mount component – Gull wing-shaped lead	26
Figure 7 – Passive array	31
Figure 8 – Pin grid array	32

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FOREWORD

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International Standard IEC 60194-2 has been prepared by IEC technical committee 91: Electronics assembly technology.

This first edition, together with IEC 60194-1, will cancel and replace IEC 60194:2015. This edition constitutes a technical revision.

This edition includes the following significant technical changes with respect to IEC 60194:2015:

- a) exclusion of 32 general terms better served by other TCs;
- b) exclusion of 47 terms no longer used by the electronics assembly industry;
- c) inclusion of 13 new terms related with device embedded substrate technology;
- d) removal of identification codes for terms as well as annexes.

The text of this International Standard is based on the following documents:

CDV	Report on voting
91/1442/CDV	91/1473/RVC

Full information on the voting for the approval of this International Standard can be found in the report on voting indicated in the above table.

This document has been drafted in accordance with the ISO/IEC Directives, Part 2.

The committee has decided that the contents of this document will remain unchanged until the stability date indicated on the IEC website under "<http://webstore.iec.ch>" in the data related to the specific document. At this date, the document will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

A bilingual version of this publication may be issued at a later date.

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1 Scope

This part of IEC 60194 covers terms and definitions related to printed board and electronic assembly technologies as well as other electronic technologies.

2 Normative references

There are no normative references in this document.